

NOVASTACK® 35-HDH

嵌合高さ 1.5 mm、0.35 mm ピッチ、フルシールド、
高速伝送対応20GHz (≒40 Gbps)/lane

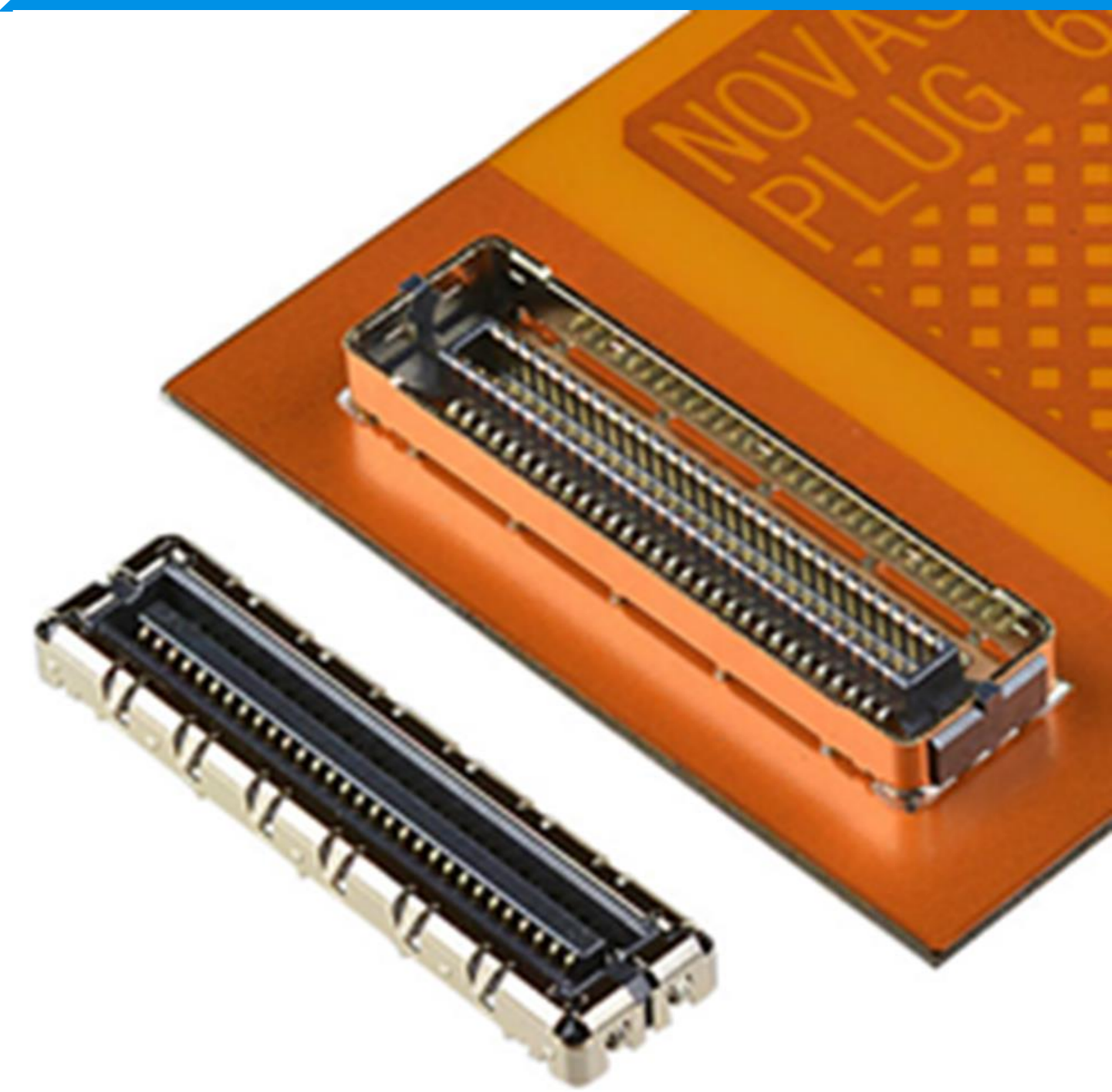
Product Specifications:

Board Pitch (mm)	0.35	
Wiping Length (mm)	0.33	
Mated Size (mm)	Height	1.5 +/- 0.10
	Width	3.3+(0.35*?p/2)
	Depth	3.64
Current Rating	Signal	0.5A/pin (12.0A Max. (Total))
	Power	-
Pin Counts	Range	10 - 70
	Available	60, 70

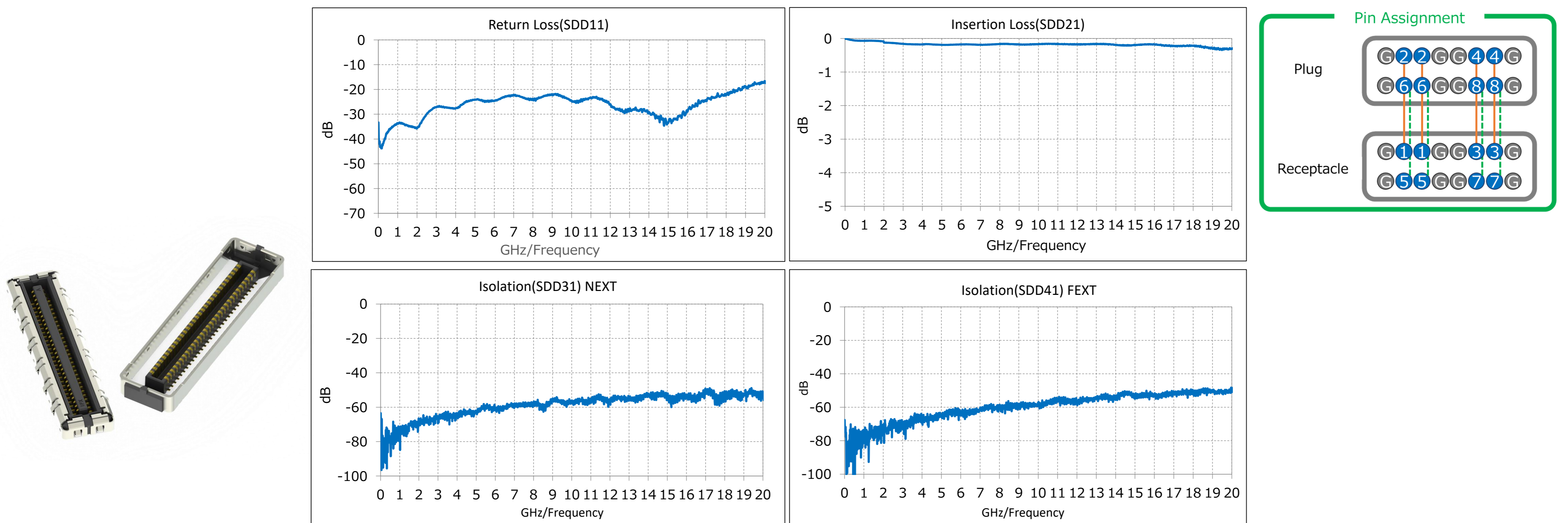
Applicable Standards (Reference Only):

USB4 (20 Gbps/lane); USB 3.1 Gen 2 (10 Gbps); eDP HBR 3 (8.1 Gbps); eDP HBR 2 (5.4 Gbps); HDMI 2.0 (6 Gbps); V-By-One HS 1.4 (4 Gbps); MiPi standards

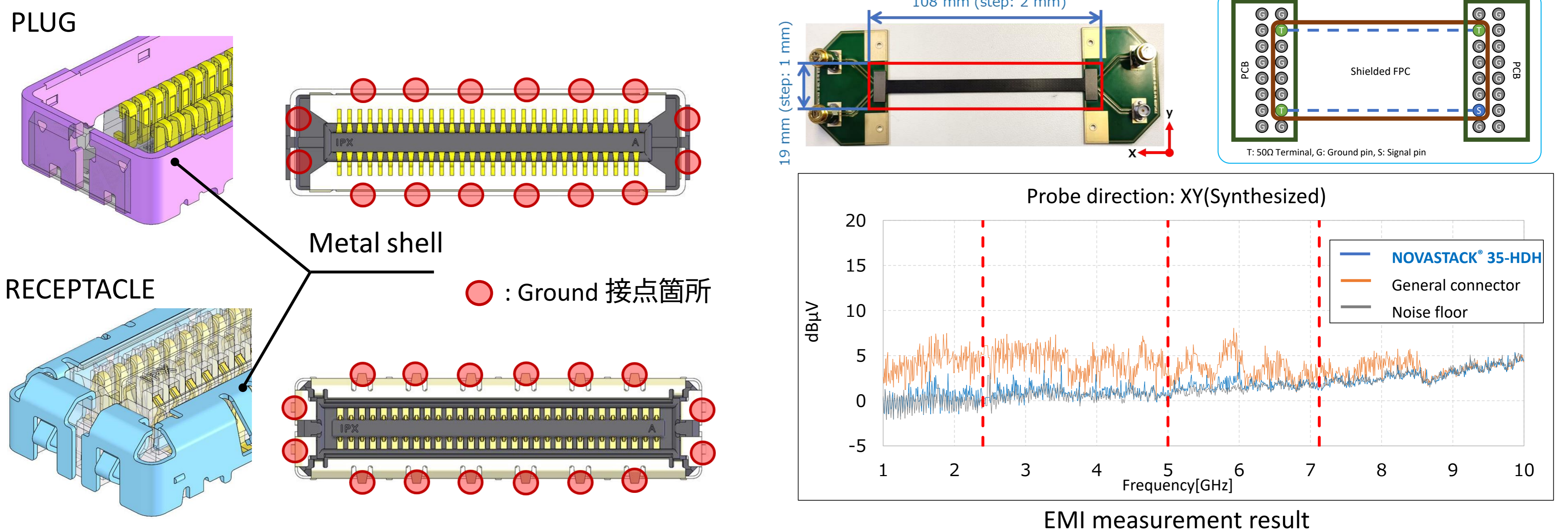
*記載のない極数の対応状況についてはお問い合わせください。



▶ 20 GHz (≒40 Gbps)/laneの伝送が可能で最新の高速信号に最適



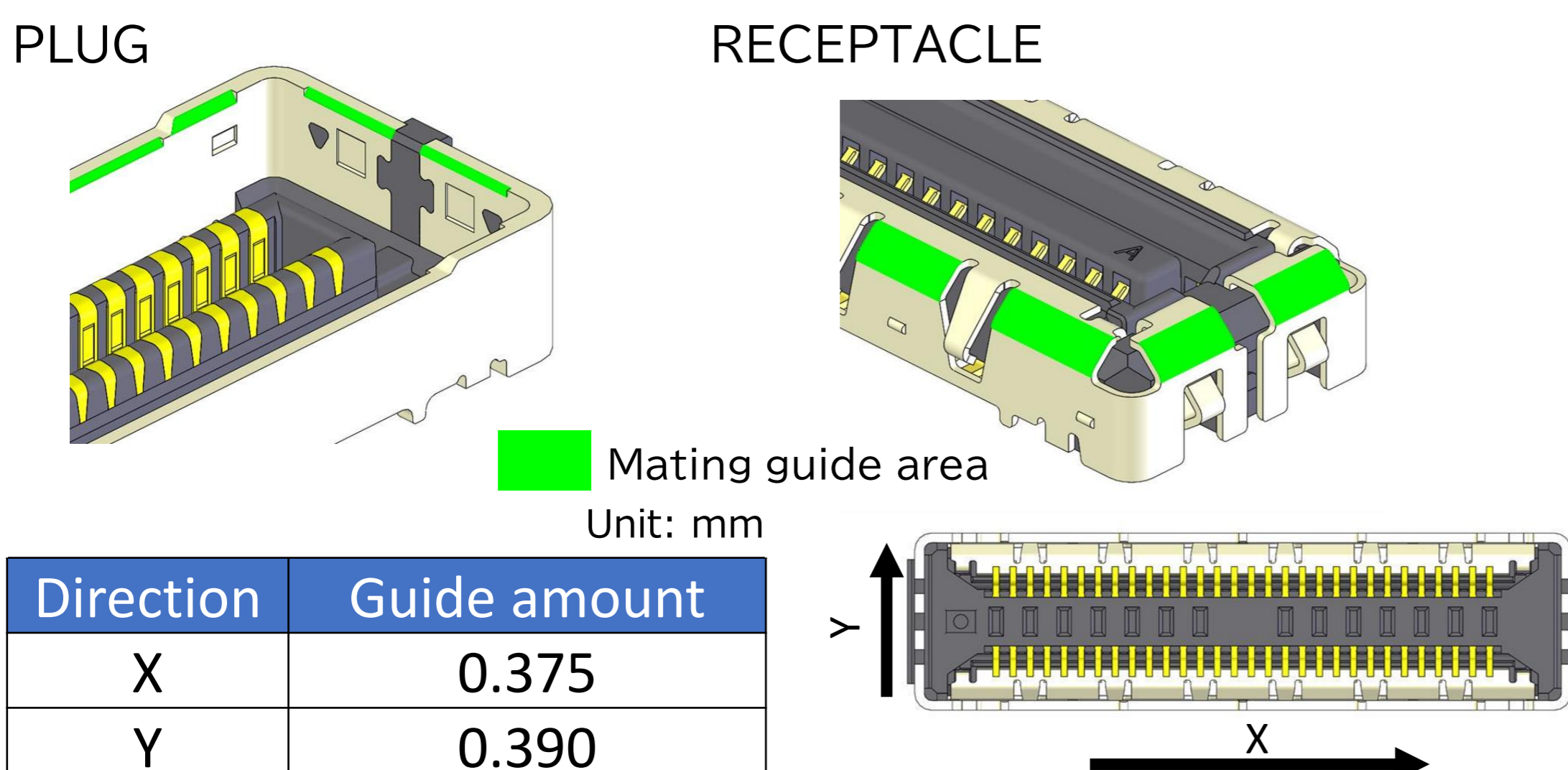
▶ 多点グラウンド接点によるZenShield® フルシールドでEMC対策



▶ 嵌合作業性に優れた設計の高背コネクタ

コンタクトピッチ以上のガイド量で適正な嵌合位置へ誘導

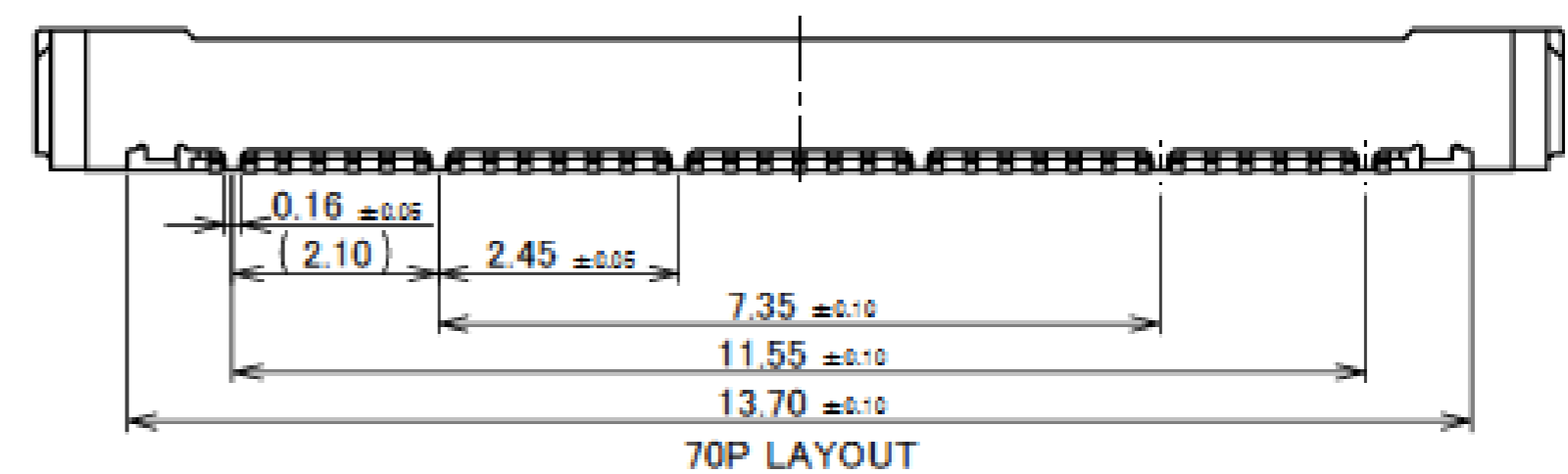
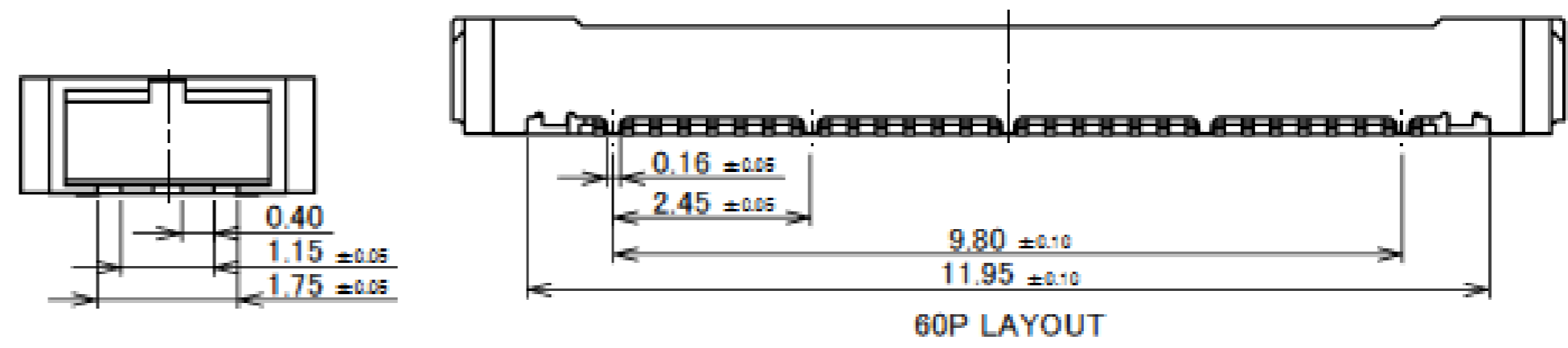
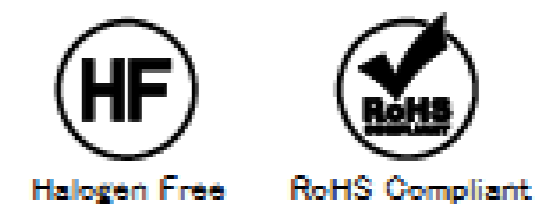
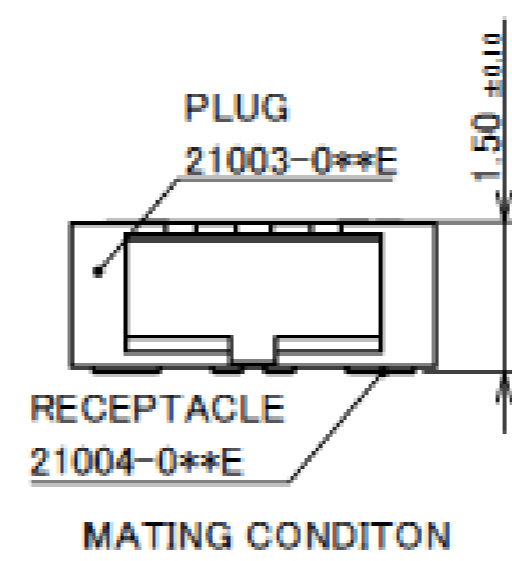
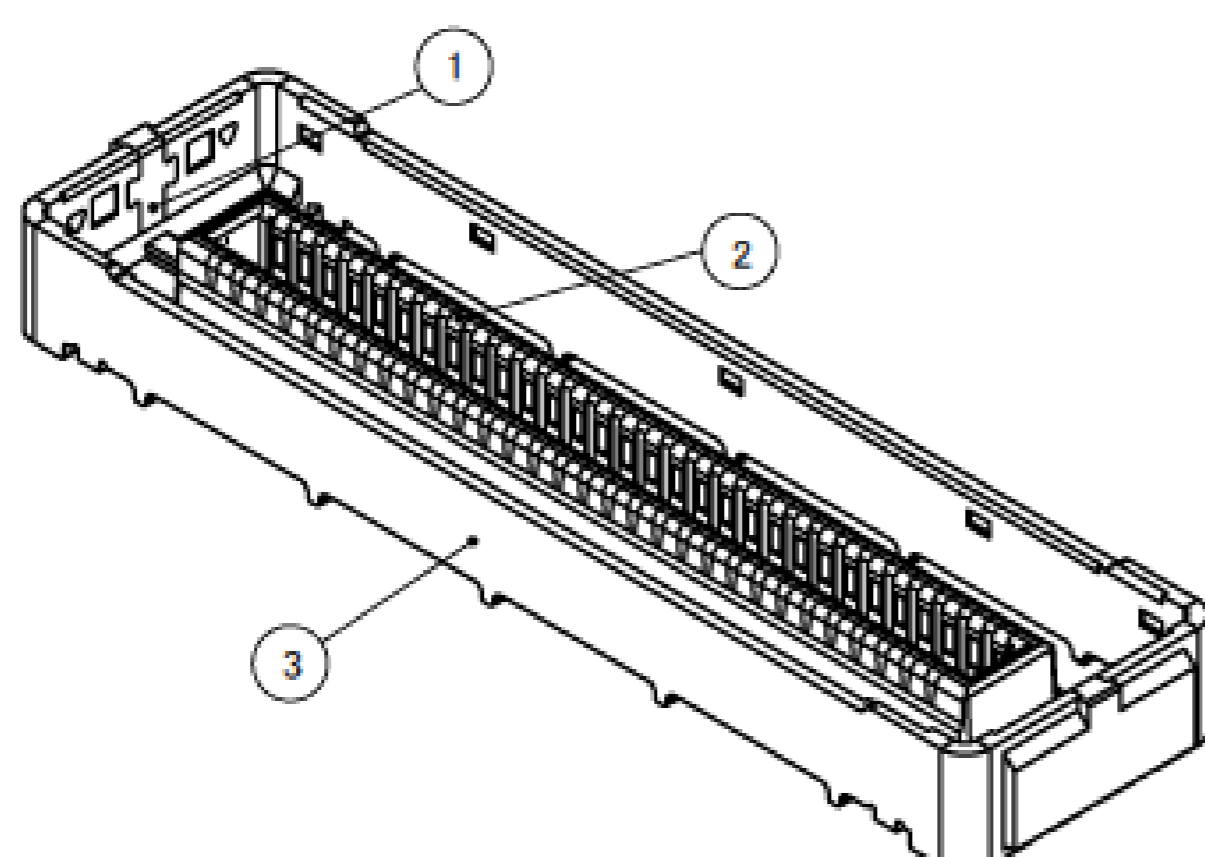
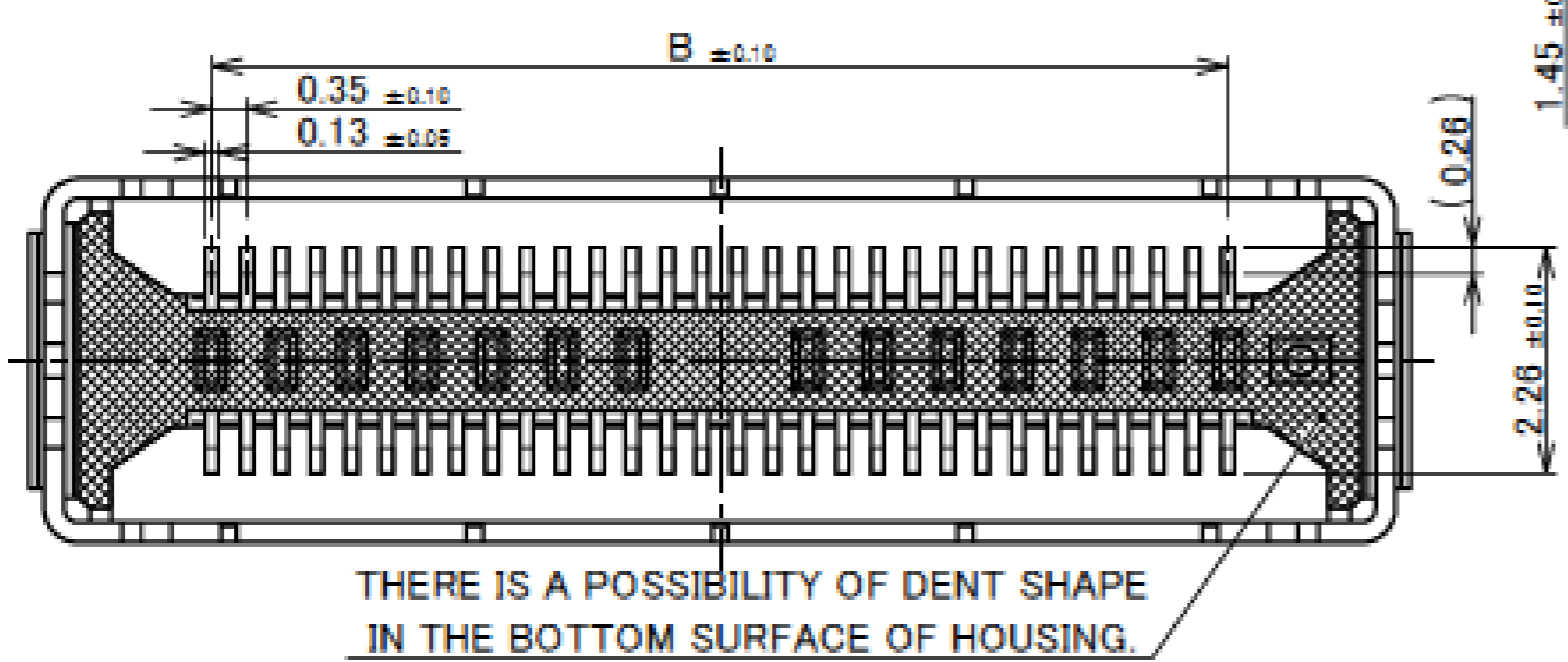
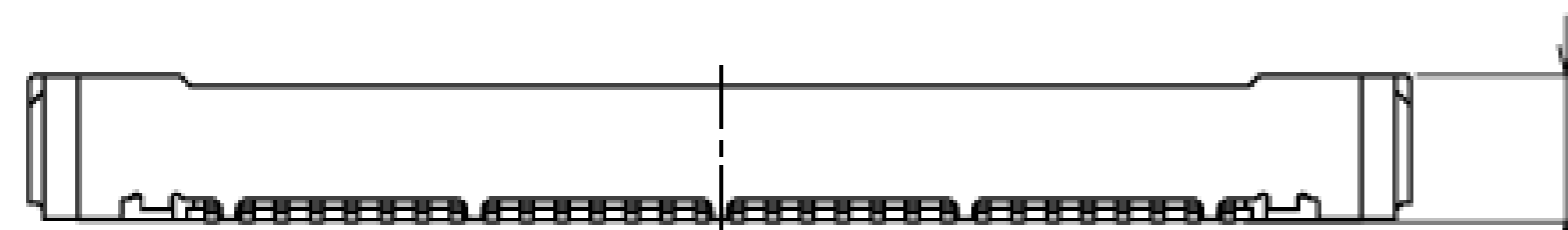
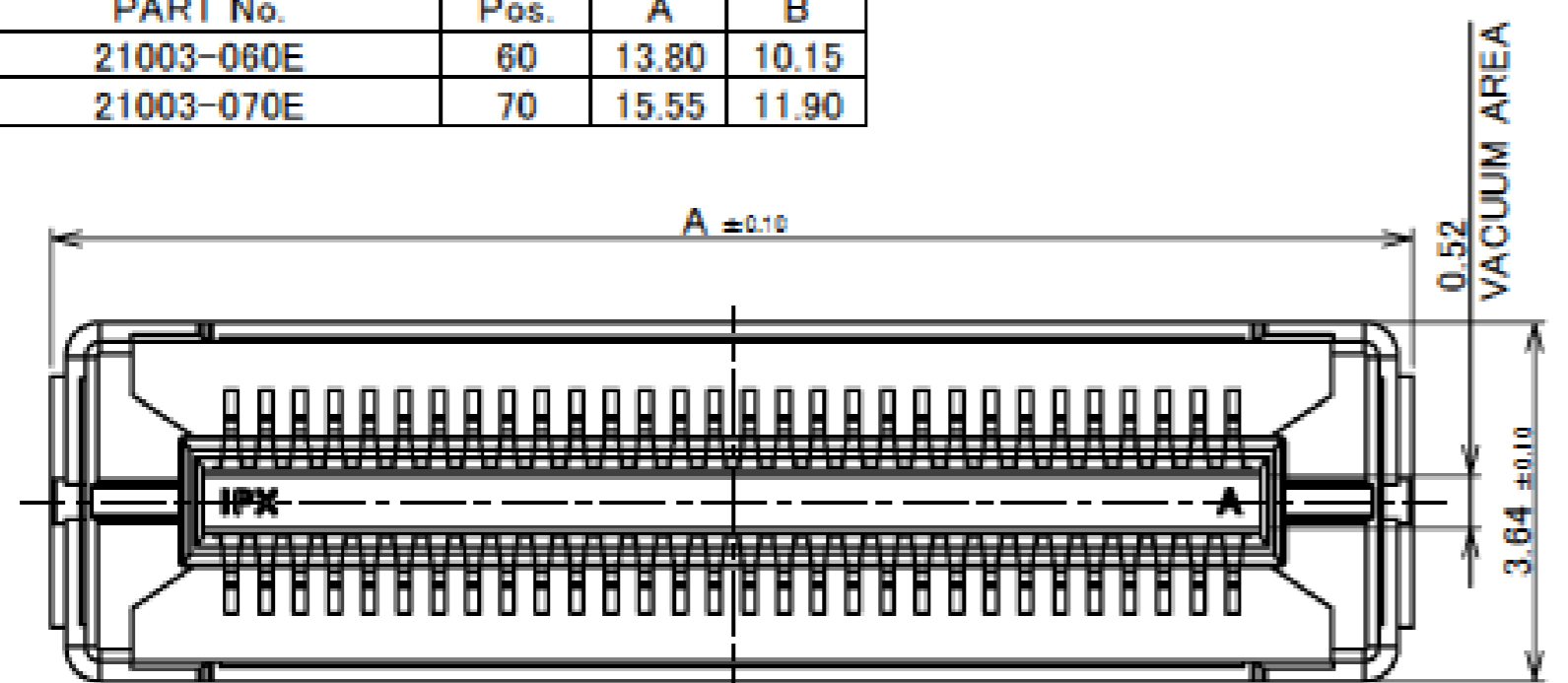
大きな有効嵌合長により嵌合傾きに強い



Component Parts Detail

Plug Assembly

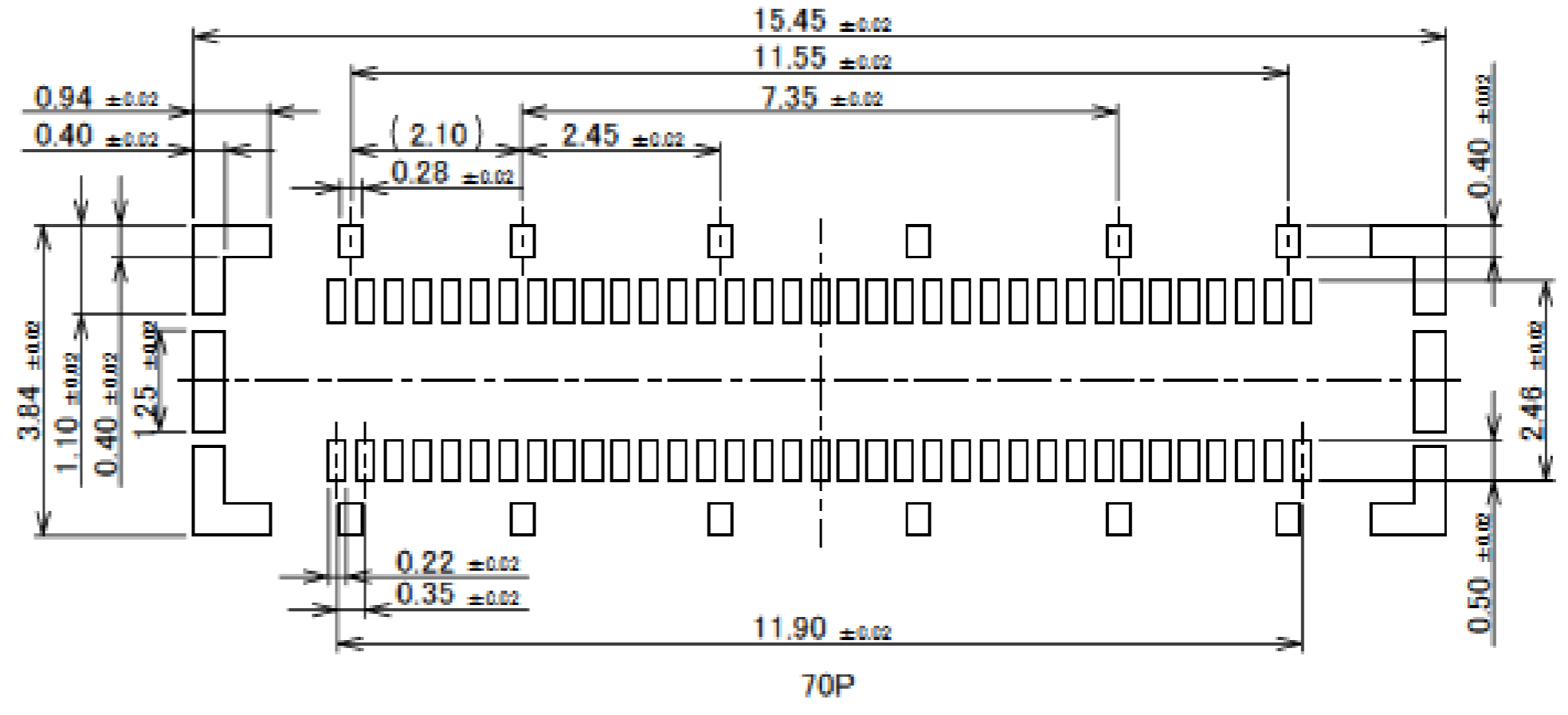
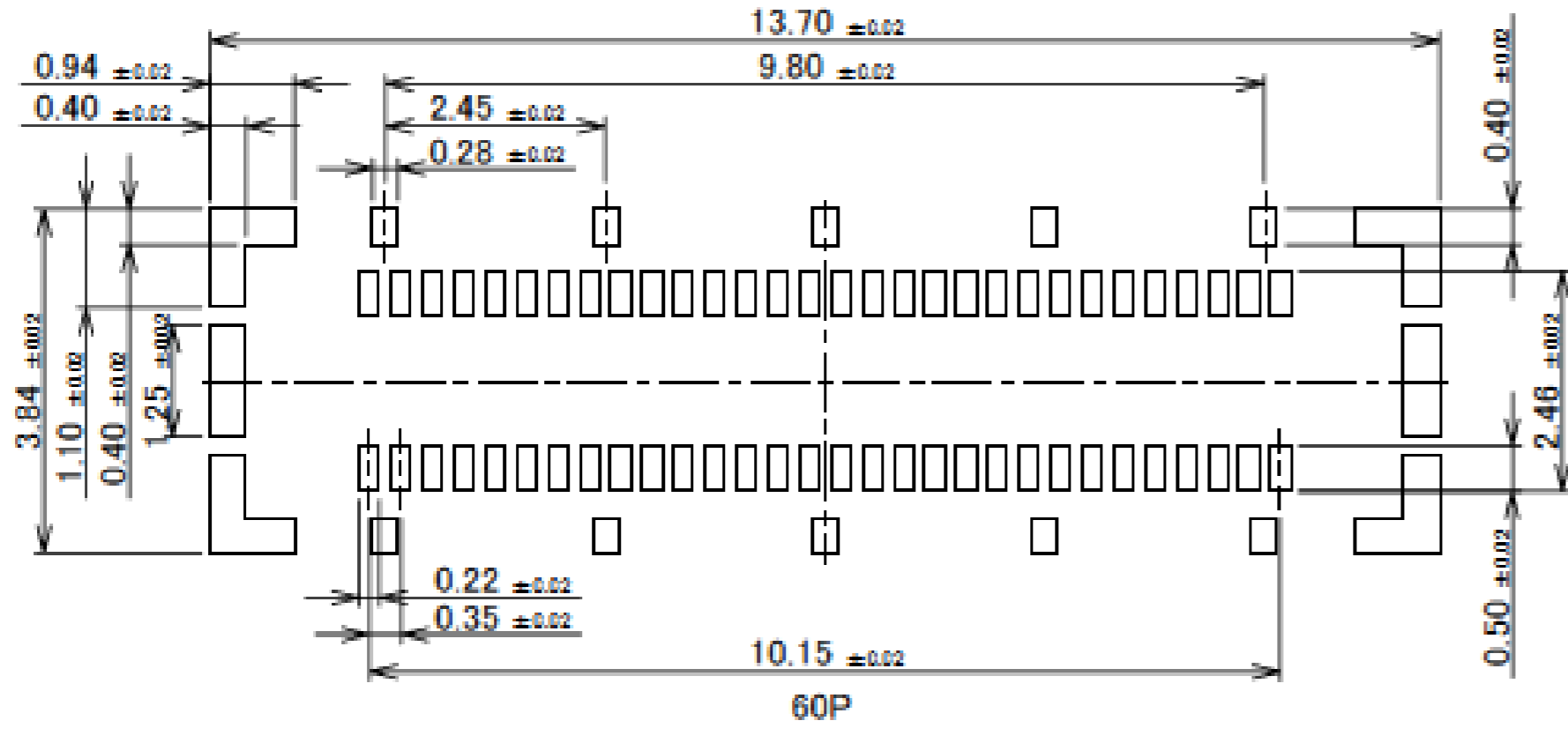
Recommended P/N		21003-0**E		
PART No.	Pos.	A	B	
21003-060E	60	13.80	10.15	
21003-070E	70	15.55	11.90	



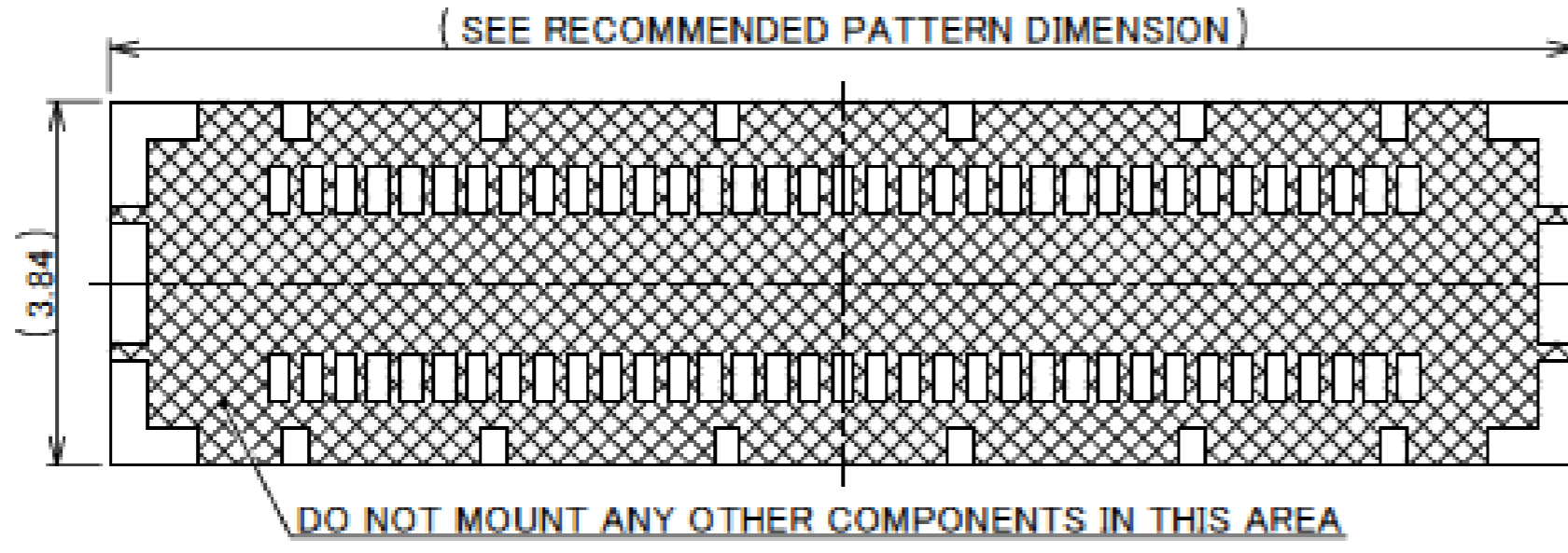
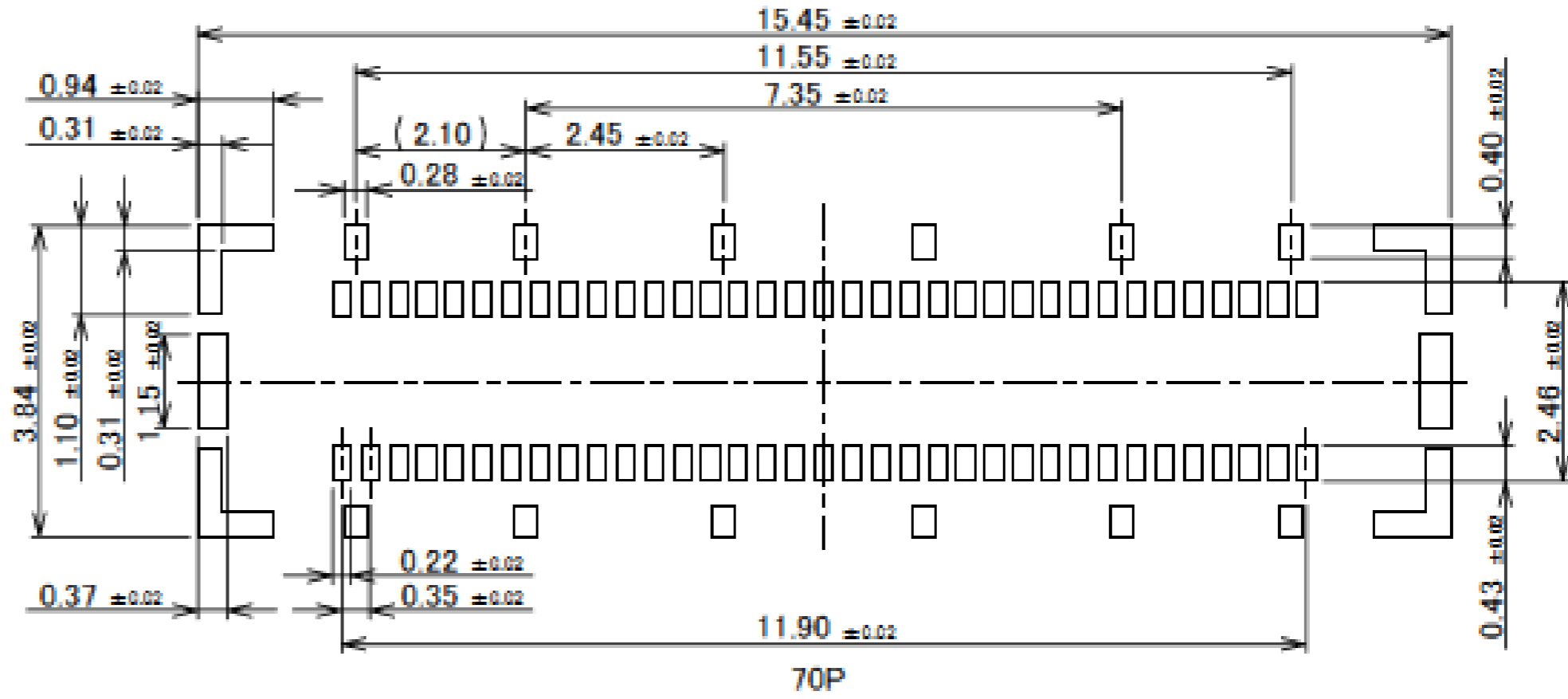
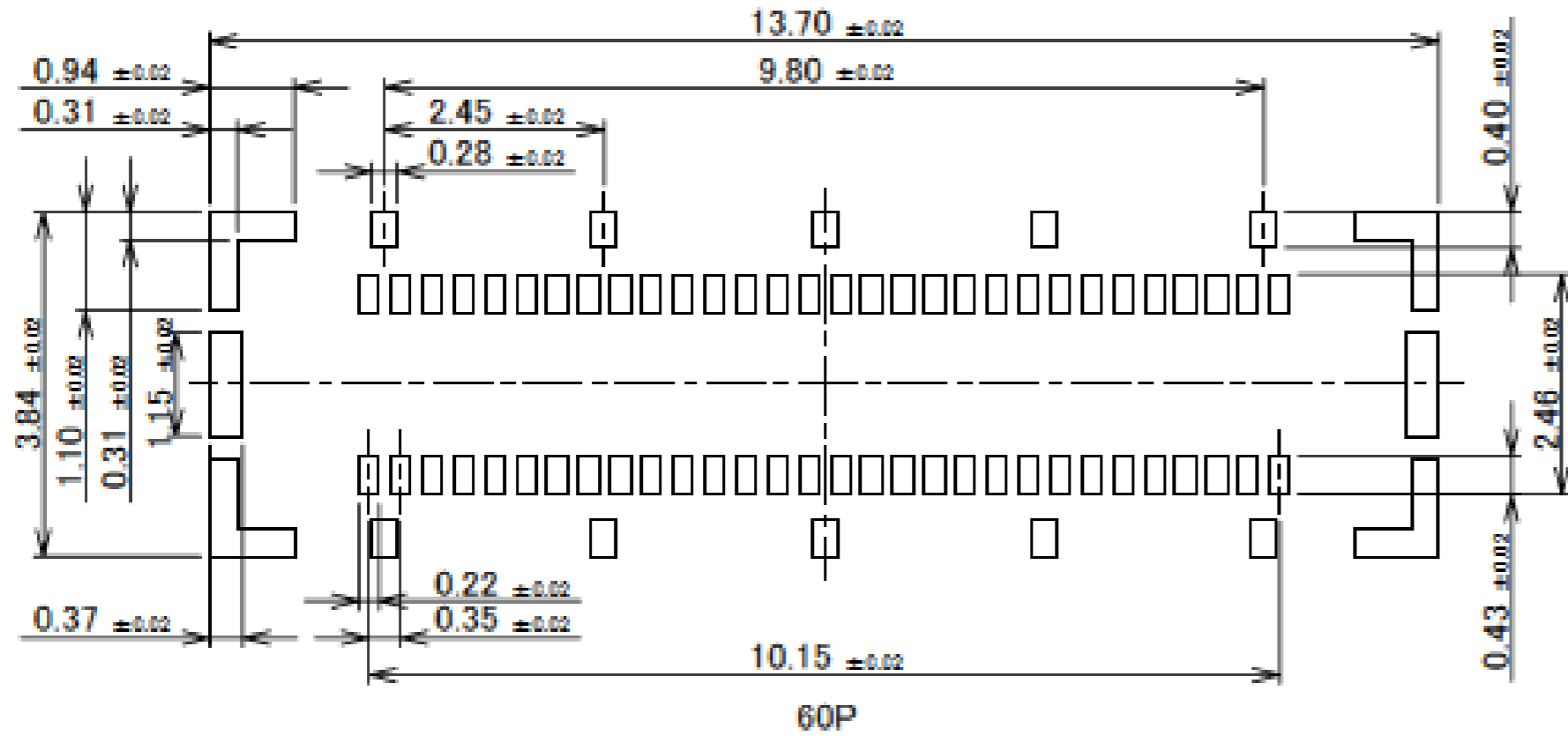
NO.	DESCRIPTION	MATERIAL	FINISH . REMARKS
3	SHELL	CORSON ALLOY	ALL Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
2	CONTACT	CORSON ALLOY	CONTACT AREA: Au 0.13 μm MIN. OVER Ni 1.27 μm MIN. SOLDERING AREA: Au 0.02 μm MIN. OVER Ni 1.27 μm MIN.
1	HOUSING	LCP	UL94V-0 BLACK

Plug Assembly

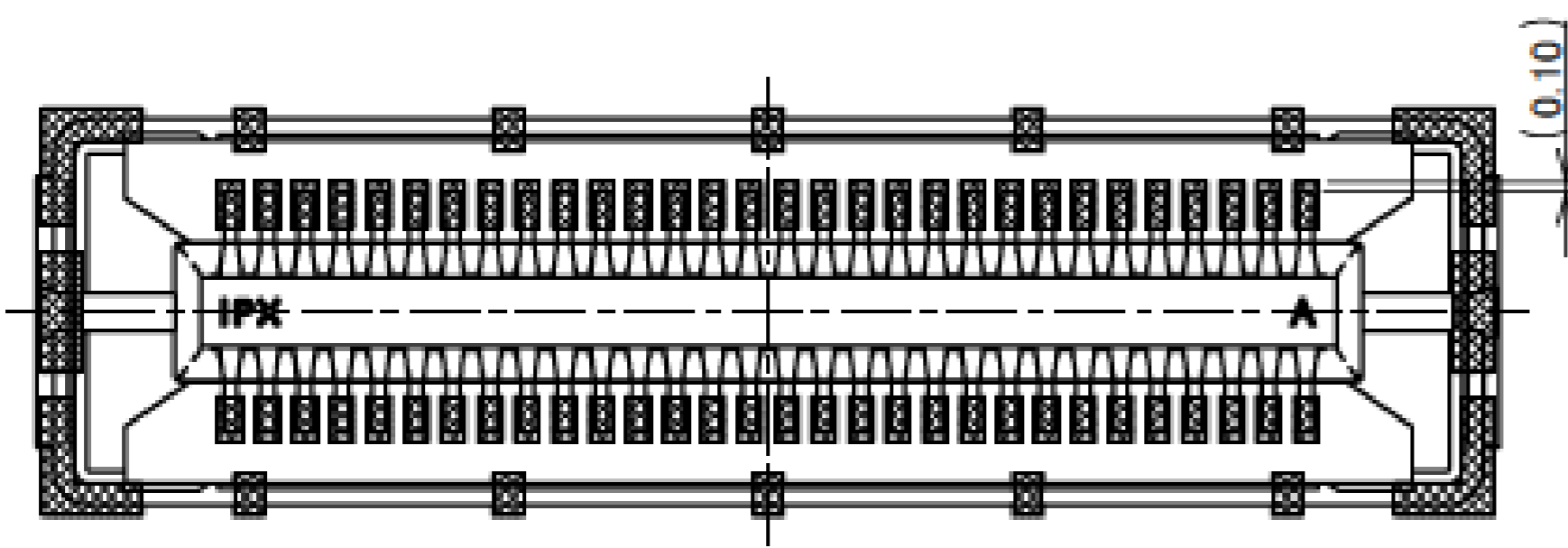
RECOMMENDED PATTERN LAYOUT



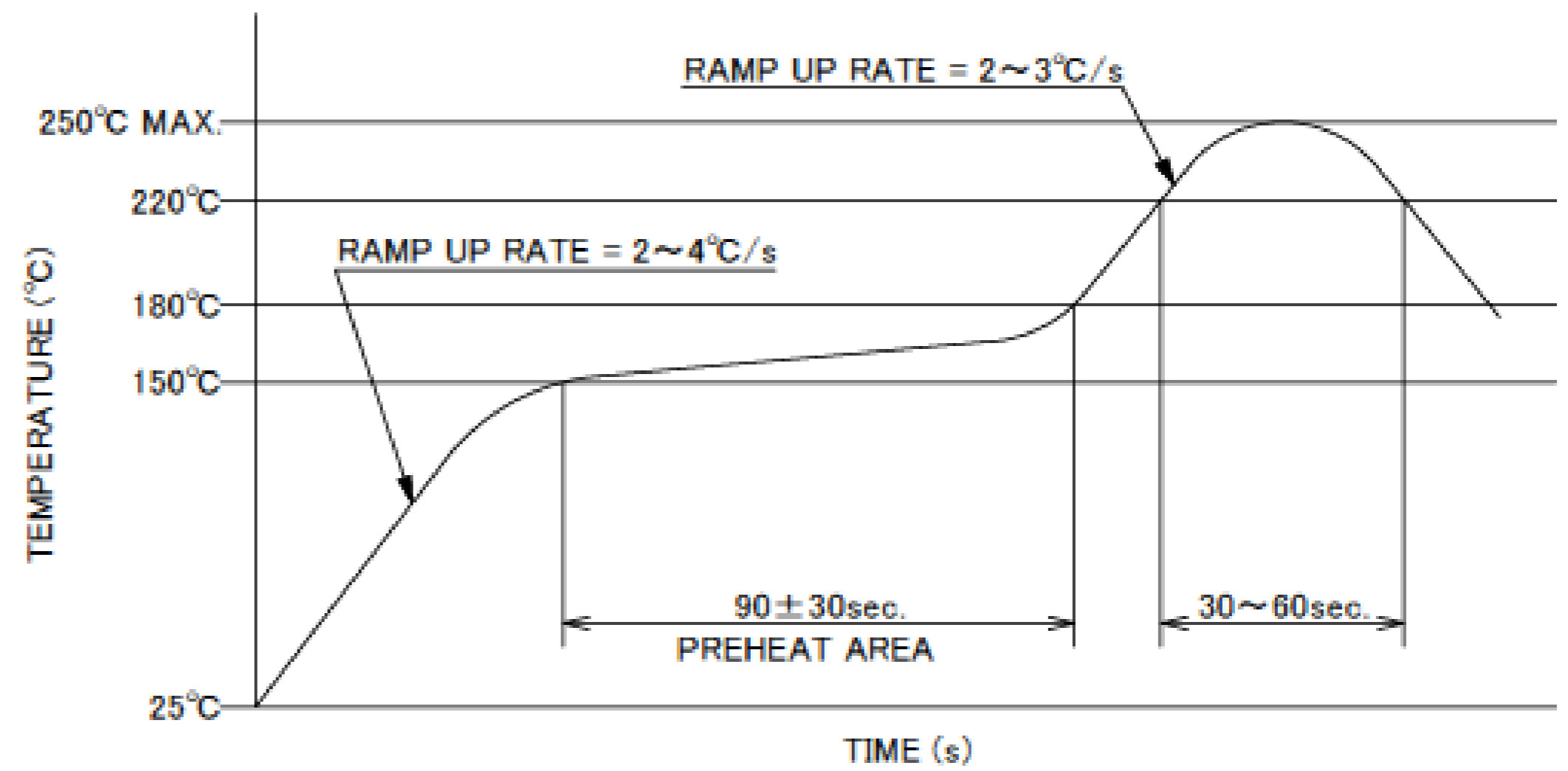
RECOMMENDED METAL MASK LAYOUT (t=0.10)



Rev.2



CONNECTOR ON RECOMMENDED FOOT PRINT PATTERN LAYOUT



REFLOW TEMPERATURE PROFILE
SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

Rev.2

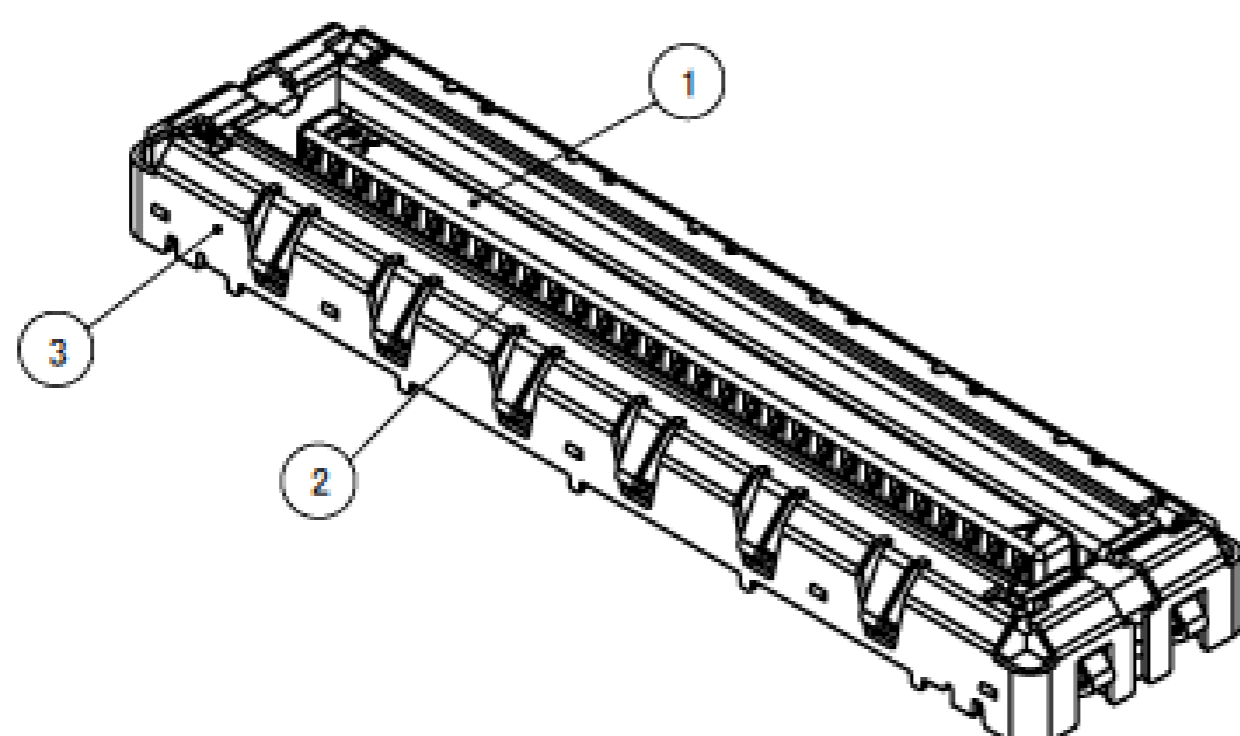
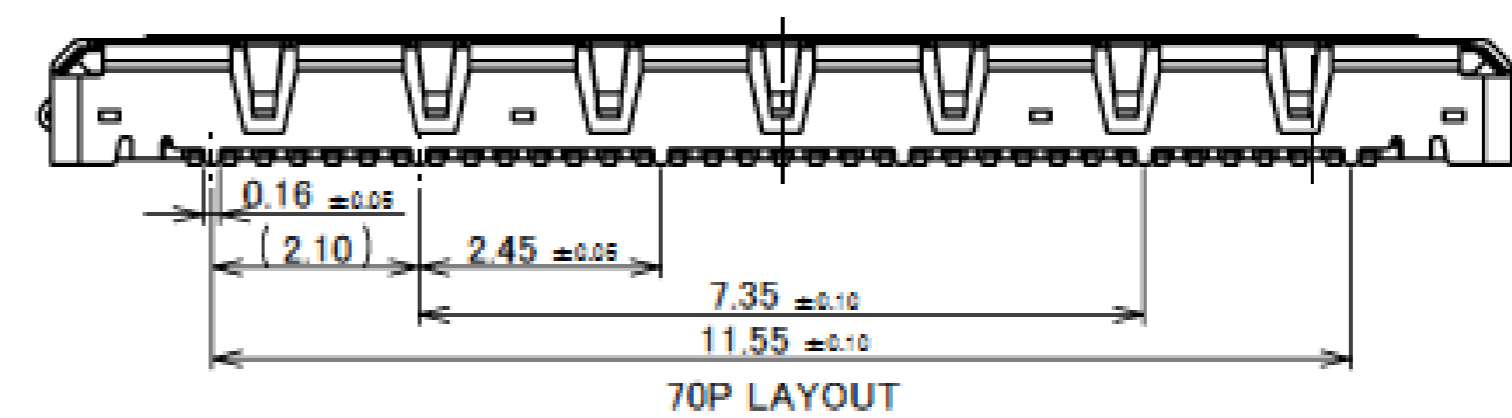
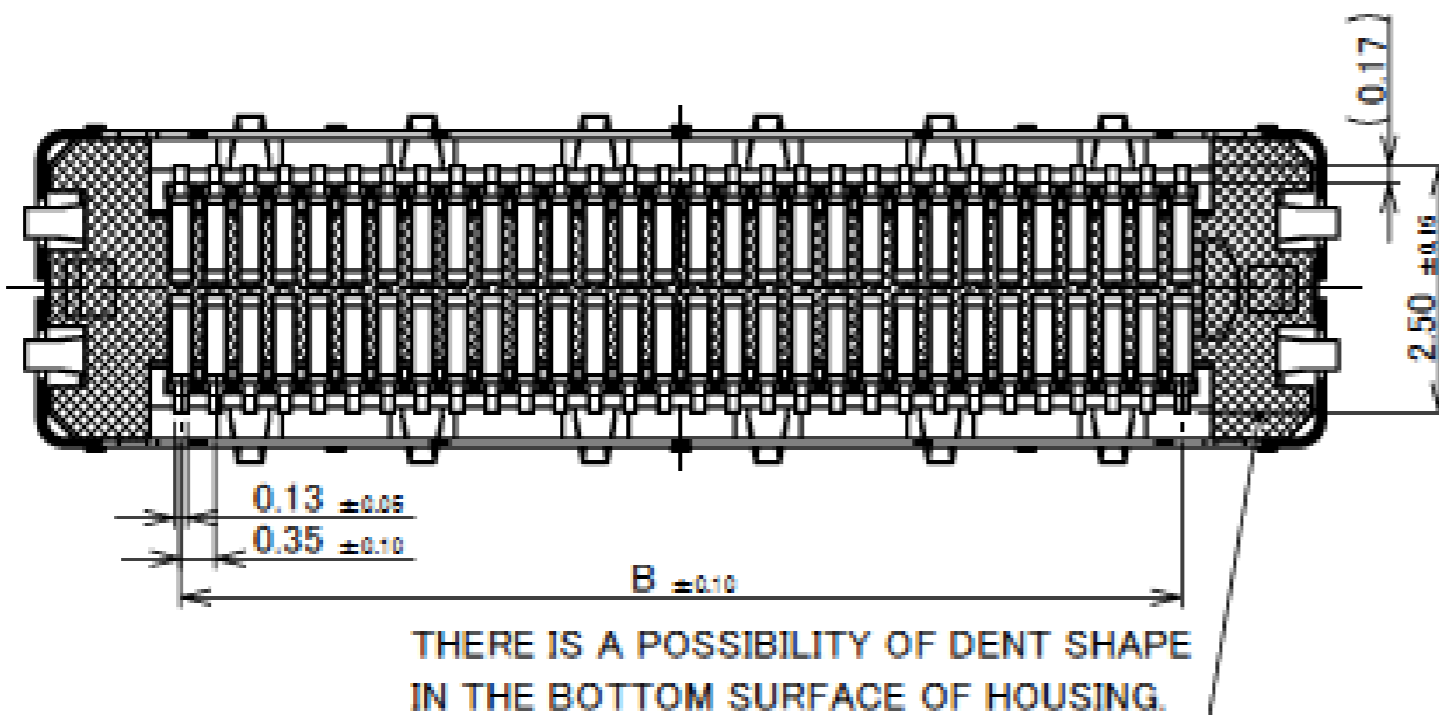
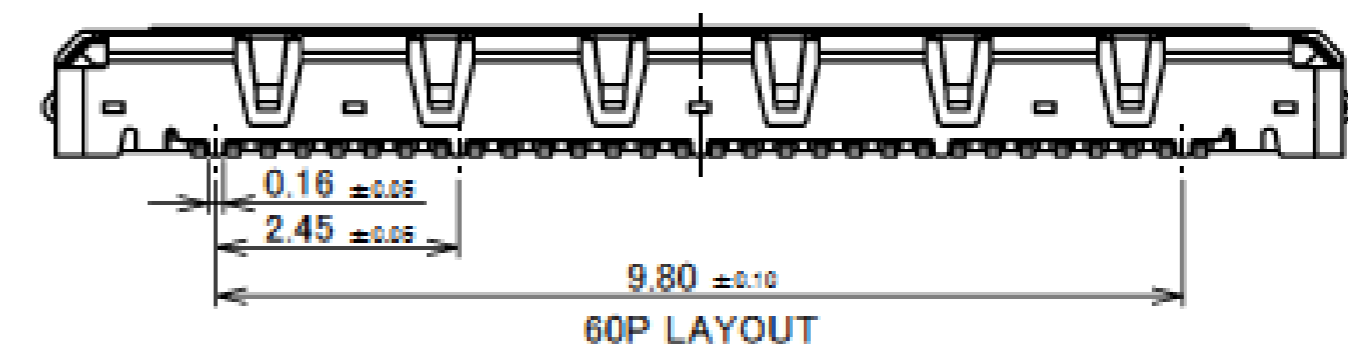
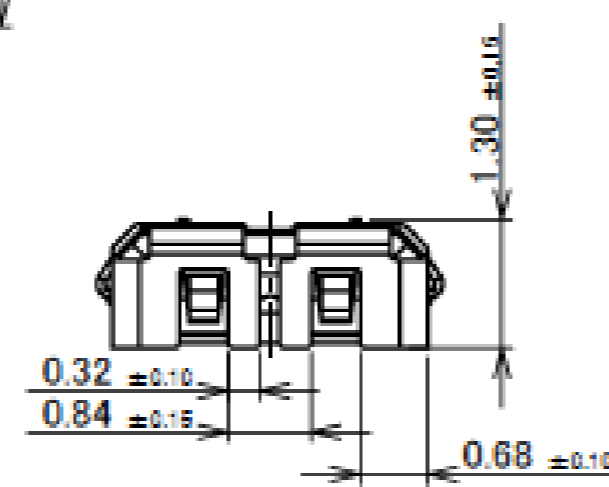
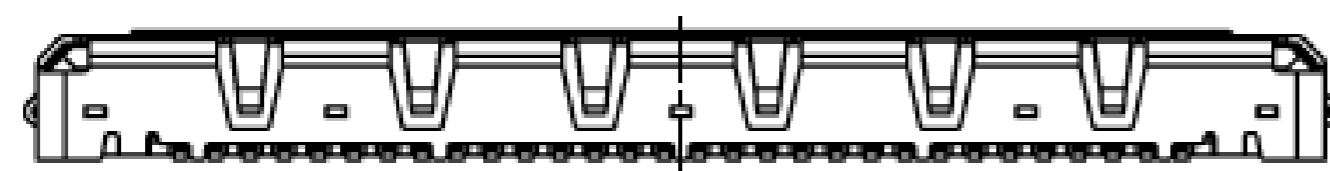
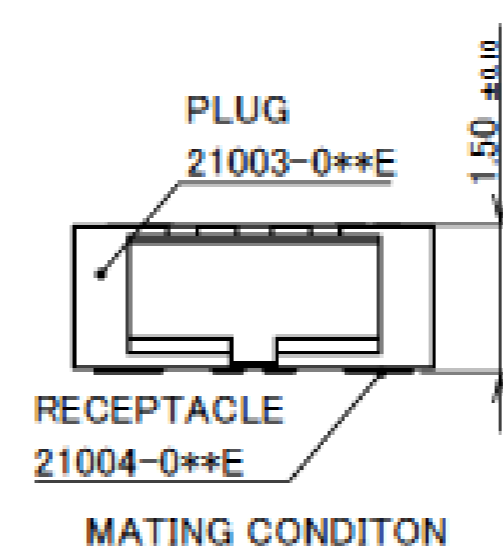
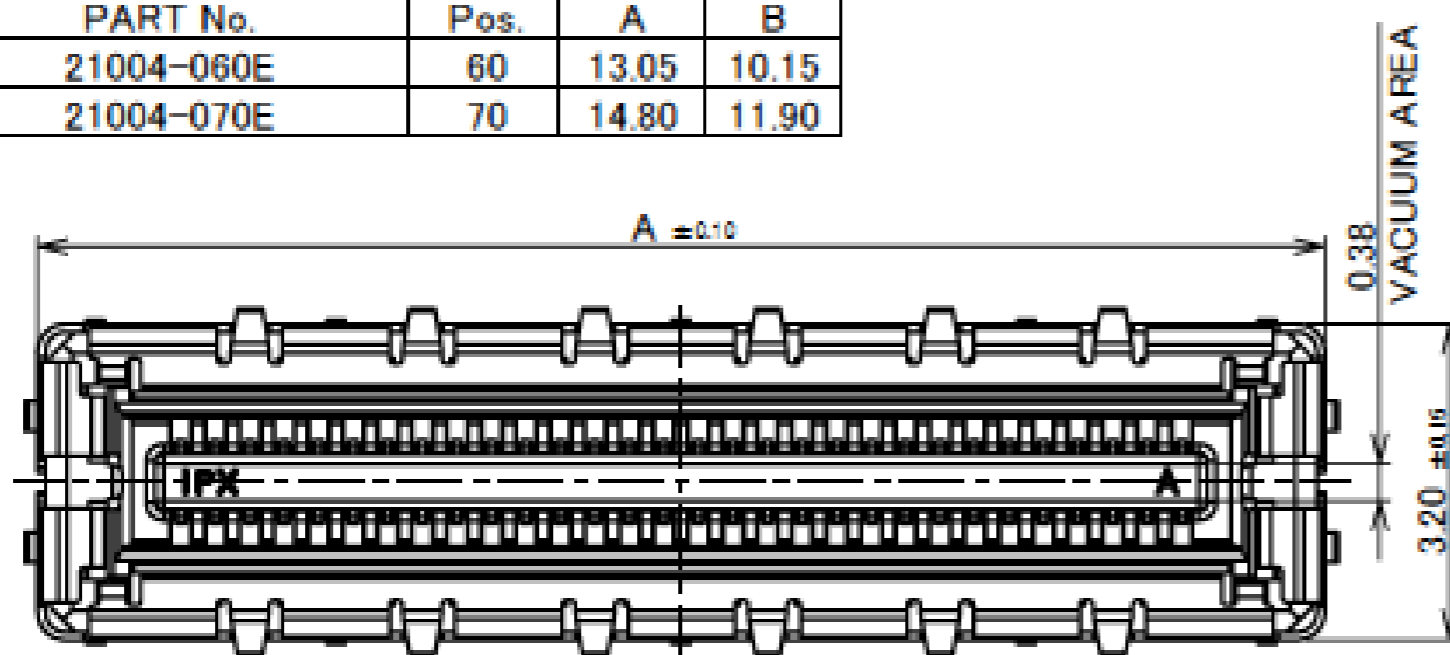
Plug Assembly

ITEMS	SPECIFICATION
APPLICABLE CONNECTOR PART No.	21004-0**E
RATING VOLTAGE	60V AC (R.M.S.)/DC (PER CONTACT PIN)
RATING AMPERAGE (FOR SIGNAL CONTACT)	0.5A AC/DC (PER CONTACT PIN)/ 12.0A AC/DC(TOTAL)
OPERATING TEMPERATURE	233~358K(-40°C~+85°C) (CONTANING TEMPERATURE RISE BY CURRENT)
OPERATING HUMIDITY	85% MAX.
CONTACT RESISTANCE (FOR SIGNAL CONTACT)	INITIAL : 50mohm MAX. / AFTER TEST : \triangle 50mohm MAX.
CONTACT RESISTANCE (FOR GROUND)	INITIAL : 20mohm MAX. / AFTER TEST : \triangle 20mohm MAX.
INSULATION RESISTANCE	INITIAL : 1000Mohm MIN. / AFTER TEST : 500Mohm MIN.
DIELECTRIC WITHSTANDING VOLTAGE	AC250V 1min
DURABILITY	20 CYCLES
MATING FORCE (INITIAL / AFTER TEST)	INITIAL 60P: 60N MAX. 70P: 70N MAX.
UNMATING FORCE (INITIAL / AFTER TEST)	20 CYCLES 60P: 6.0N MIN. 70P: 7.0N MIN.
COPLANARITY	0.10mm MAX.
PRODUCT SPECIFICATION	PRS-2785
TEST REPORT	TR-22021
PACKING STANDARD	PST-21086
INSTRUCTION MANUAL	HIM-21015
APPEARANCE CRITERIA No.	QLS-A***

Rev.2

Receptacle Assembly

Recommended P/N	21004-0**E		
PART No.	Pos.	A	B
21004-060E	60	13.05	10.15
21004-070E	70	14.80	11.90

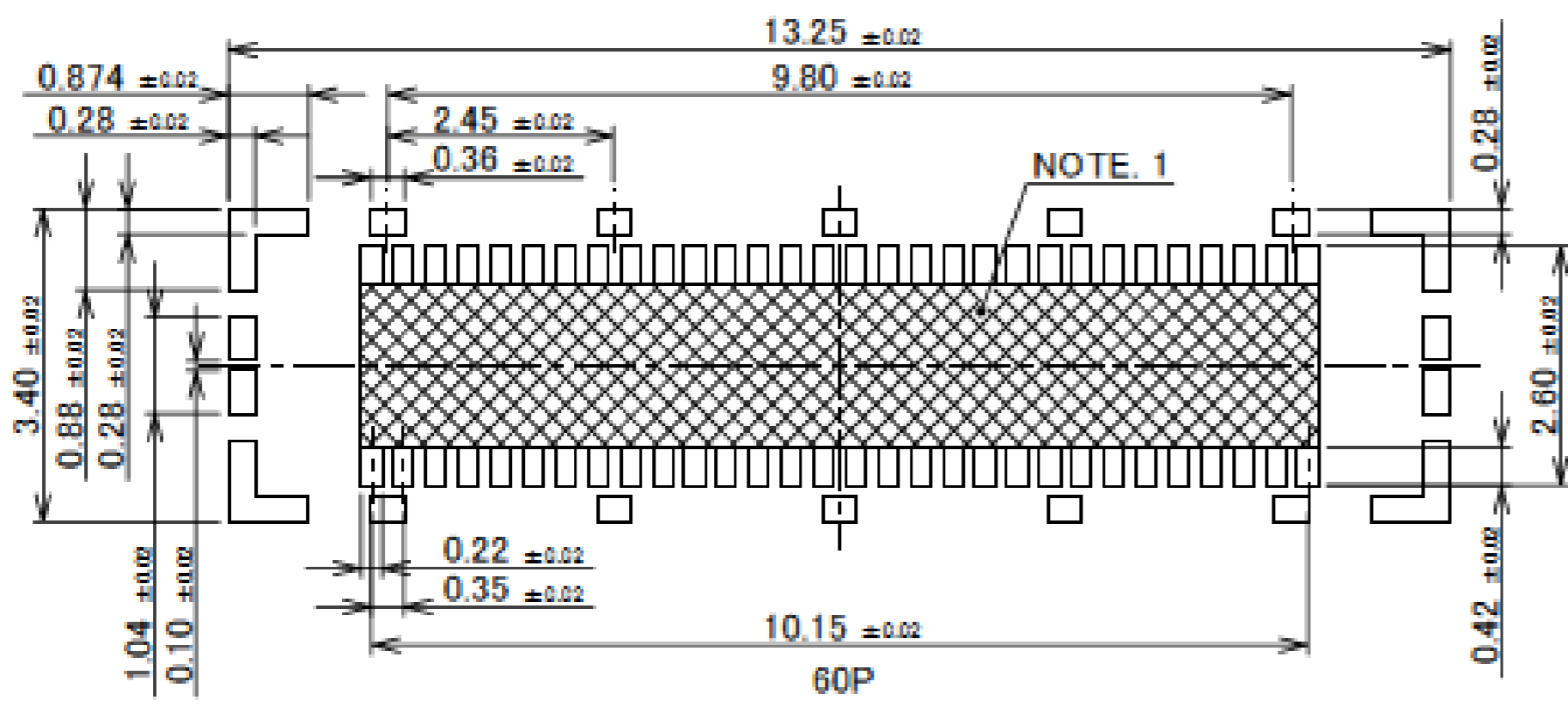


3	SHELL	CORSON ALLOY	ALL Au 0.01 μ m MIN. OVER Ni 1.27 μ m MIN.
2	CONTACT	CORSON ALLOY	CONTACT AREA: Au 0.13 μ m MIN. OVER Ni 1.27 μ m MIN. SOLDERING AREA: Au 0.02 μ m MIN. OVER Ni 1.27 μ m MIN.
1	HOUSING	LCP	UL94V-0 BLACK
NO.	DESCRIPTION	MATERIAL	FINISH , REMARKS

Rev.2

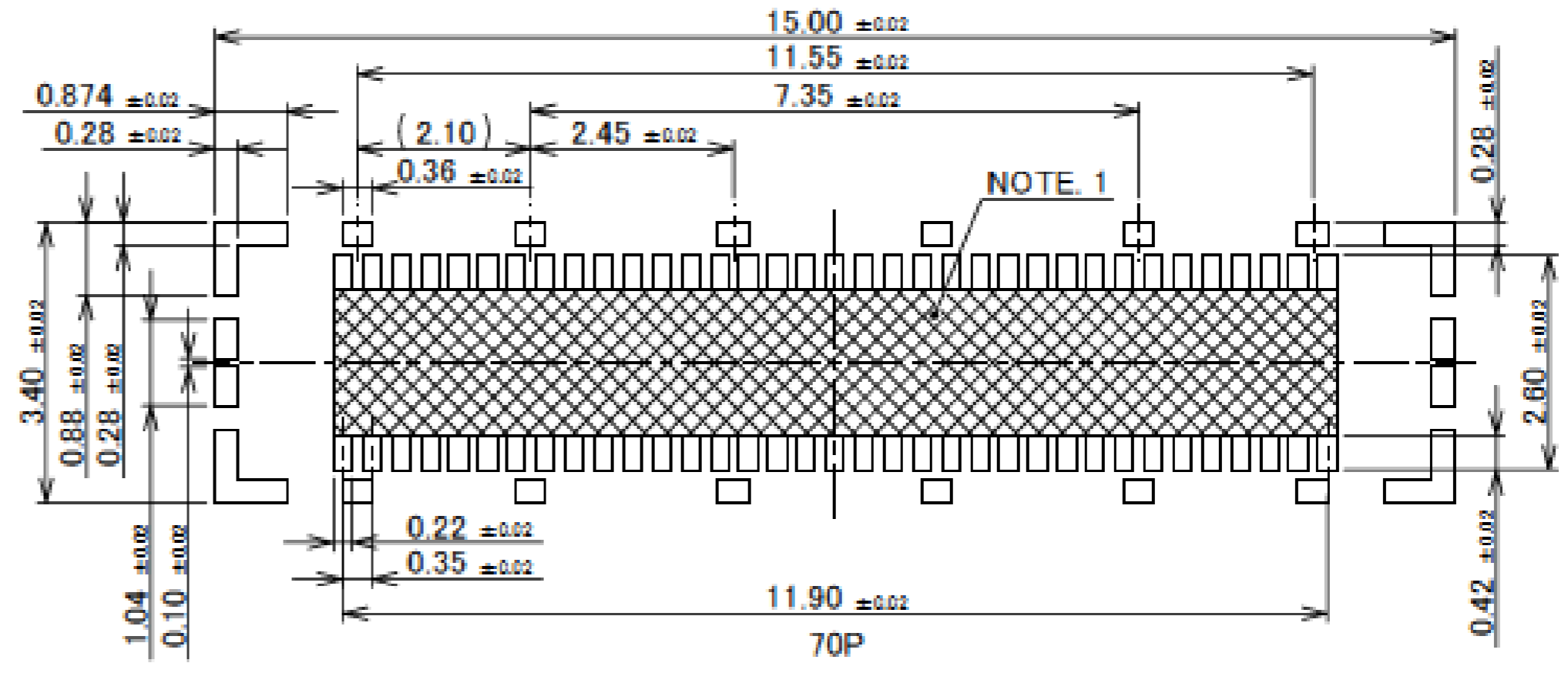
Receptacle Assembly

RECOMMENDED PATTERN LAYOUT

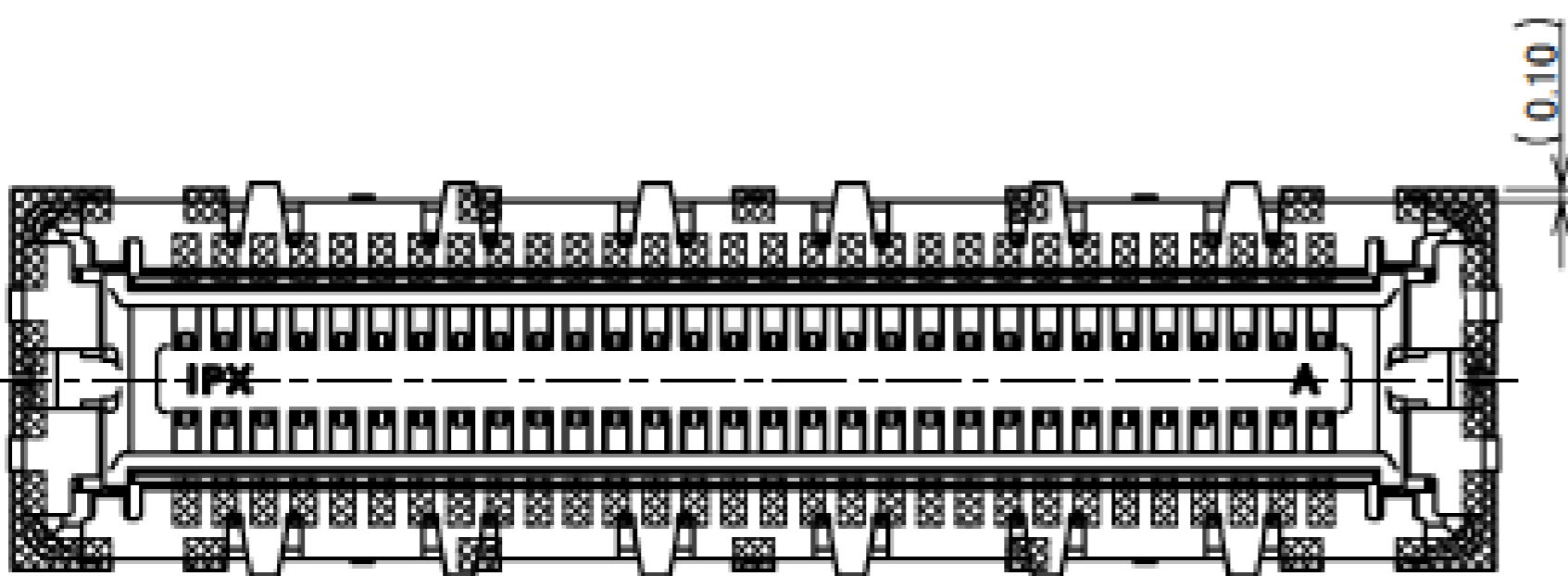
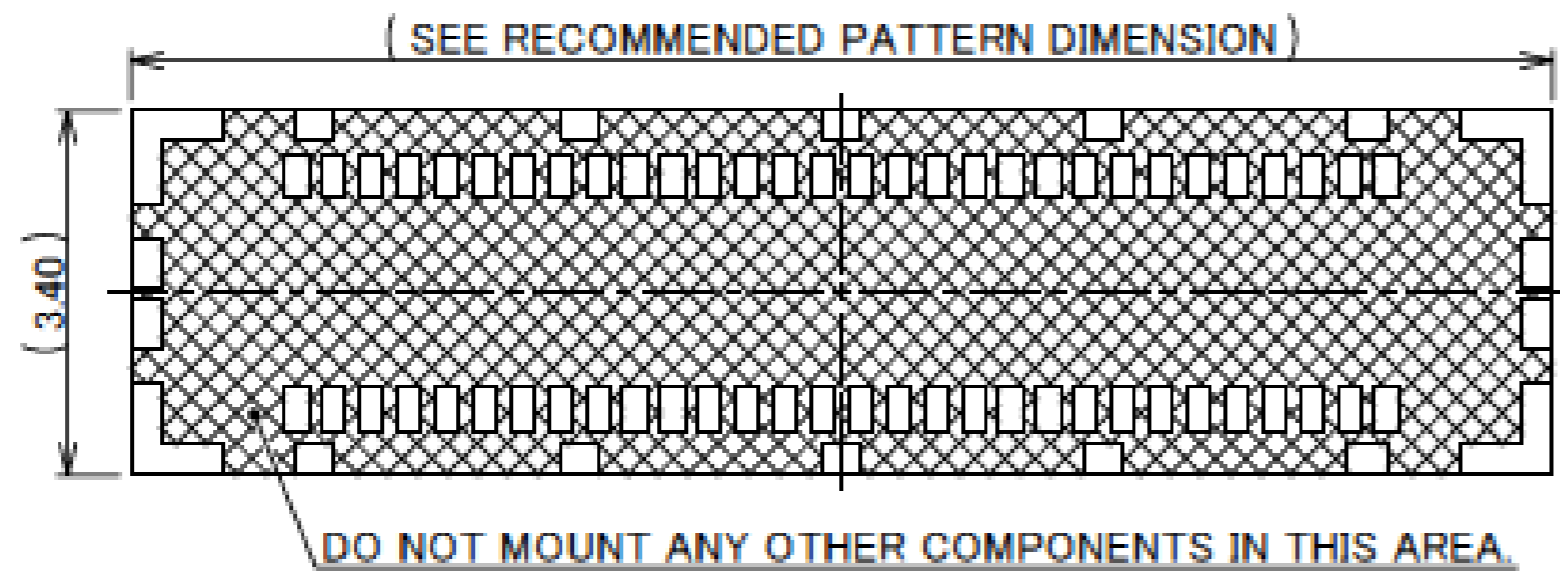
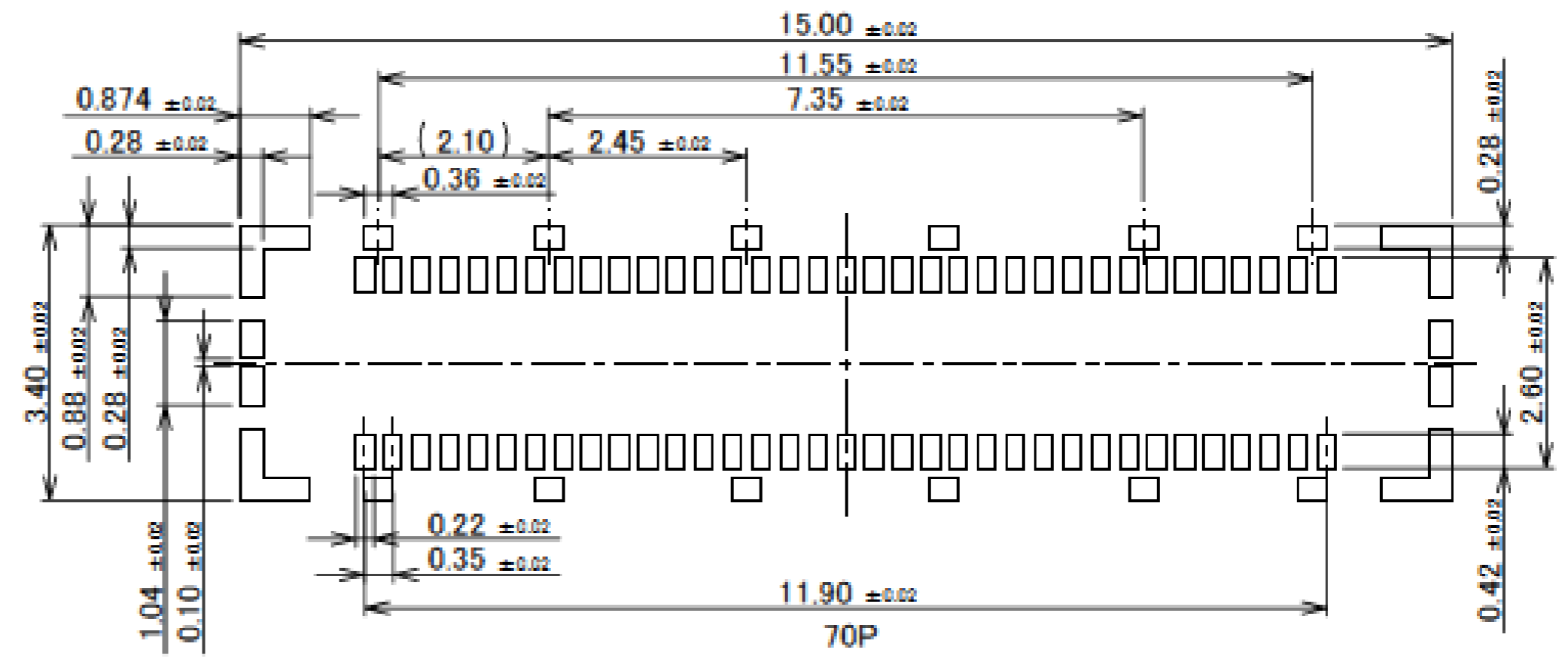
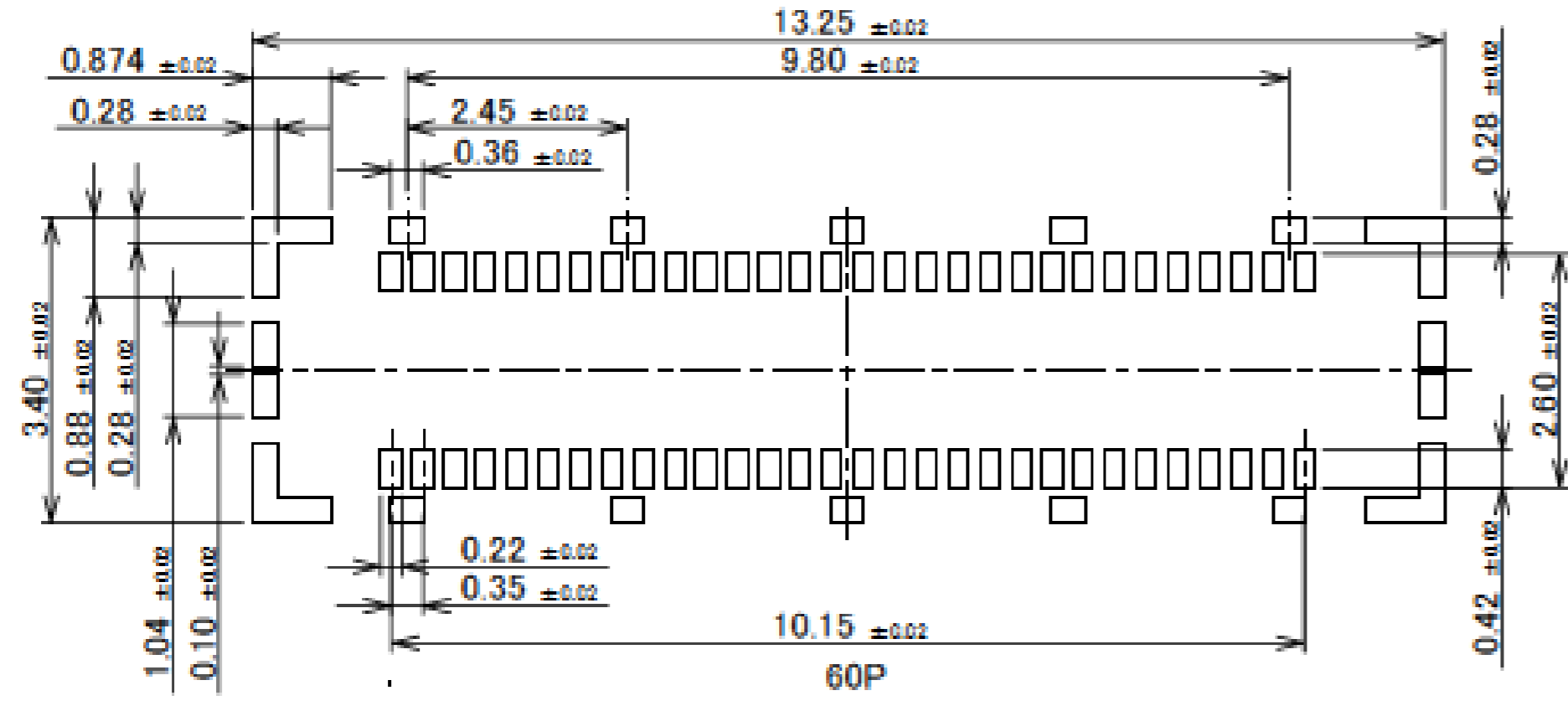


NOTES

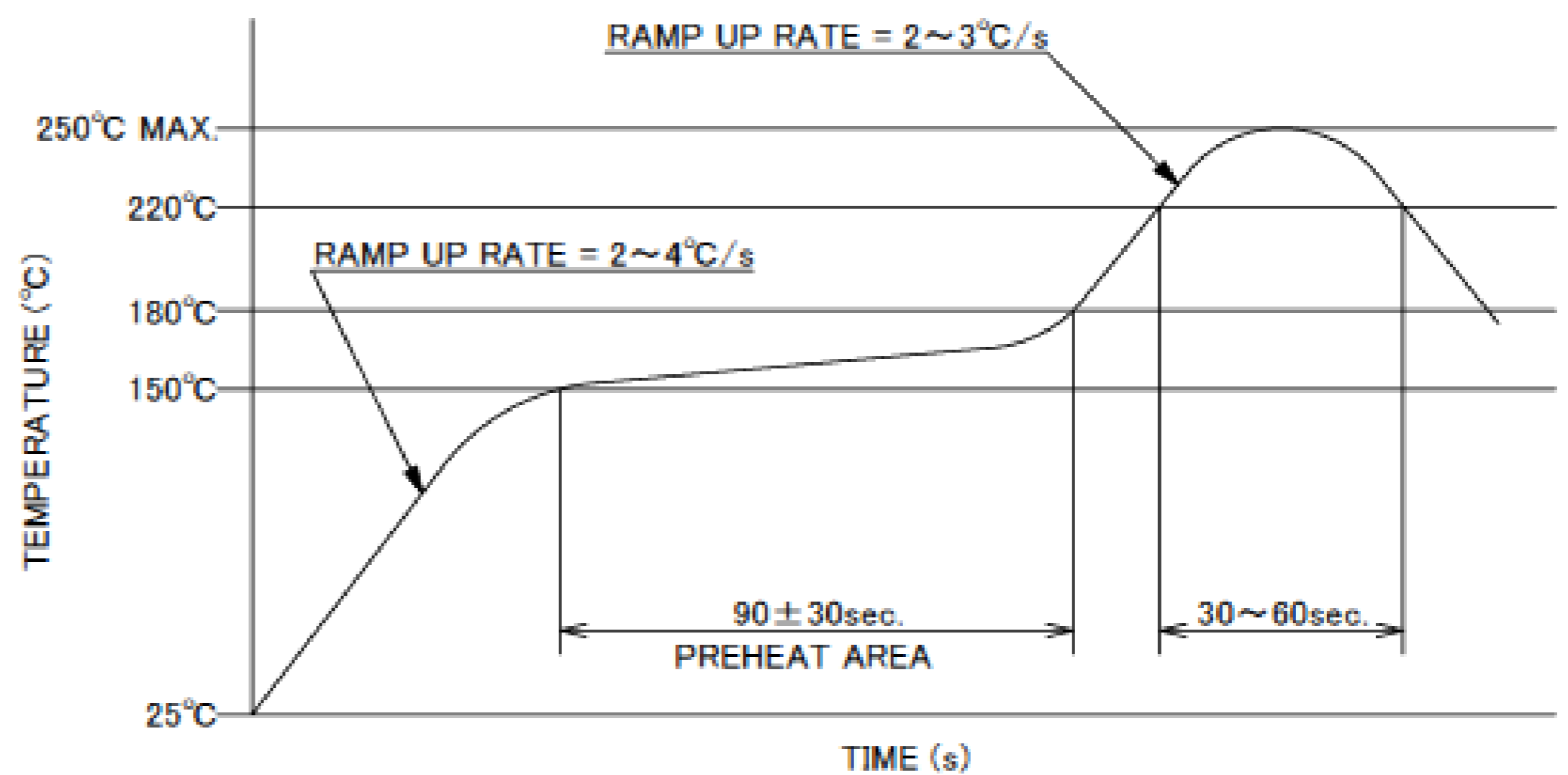
1. FOOT PRINT PATTERN PROHIBITION AREA
SOLDER RESIST MUST BE APPLIED TO THIS HATCHED AREA IF SURFACE TRACES ARE ROUNDED.



RECOMMENDED METAL MASK LAYOUT (t=0.10)



CONNECTOR ON RECOMMENDED FOOTPRINT PATTERN LAYOUT



REFLOW TEMPERATURE PROFILE
SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

Rev.2

Rev.2

Receptacle Assembly

ITEMS	SPECIFICATION
APPLICABLE CONNECTOR PART No.	21003-0**E
RATING VOLTAGE	60V AC (R.M.S.)/DC (PER CONTACT PIN)
RATING AMPERAGE (FOR SIGNAL CONTACT)	0.5A AC/DC (PER CONTACT PIN)/ 12.0A AC/DC(TOTAL)
OPERATING TEMPERATURE	233~358K(-40°C~+85°C) (CONTANING TEMPERATURE RISE BY CURRENT)
OPERATING HUMIDITY	85% MAX.
CONTACT RESISTANCE (FOR SIGNAL CONTACT)	INITIAL : 50mohm MAX. / AFTER TEST : Δ 50mohm MAX.
CONTACT RESISTANCE (FOR GROUND)	INITIAL : 20mohm MAX. / AFTER TEST : Δ 20mohm MAX.
INSULATION RESISTANCE	INITIAL : 1000Mohm MIN. / AFTER TEST : 500Mohm MIN.
DIELECTRIC WITHSTANDING VOLTAGE	AC250V 1min
DURABILITY	20 CYCLES
MATING FORCE (INITIAL / AFTER TEST)	INITIAL 60P: 60N MAX. 70P: 70N MAX.
UNMATING FORCE (INITIAL / AFTER TEST)	20 CYCLES 60P: 6.0N MIN. 70P: 7.0N MIN.
COPLANARITY	0.10mm MAX.
PRODUCT SPECIFICATION	PRS-2785
TEST REPORT	TR-22021
PACKING STANDARD	PST-21087
INSTRUCTION MANUAL	HIM-21015
APPEARANCE CRITERIA No.	QLS-A***

Rev.2

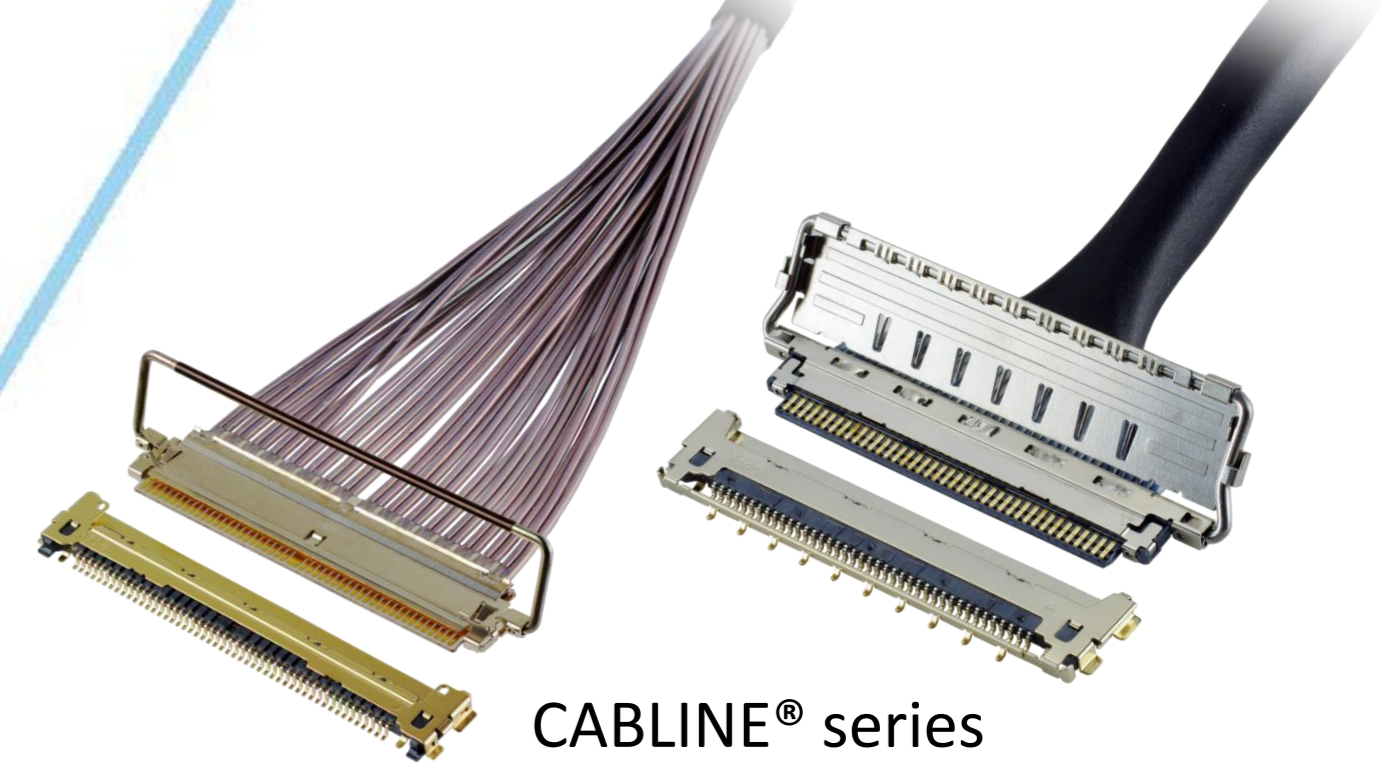
Custom Products Available

RF Connector

MHF® series



Micro-coaxial/Twinax/Discrete Wire Connector



CABLINE® series

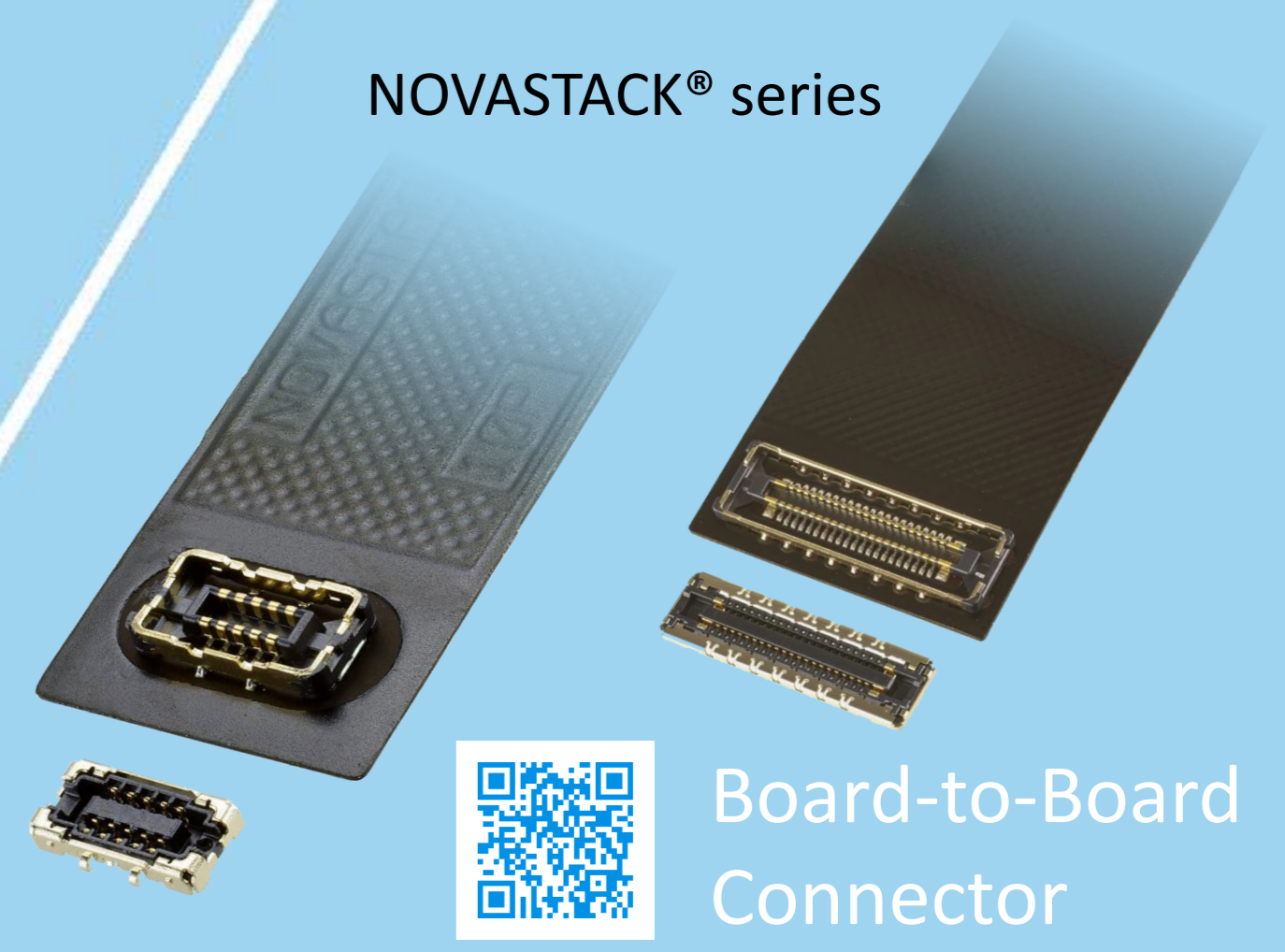


Optical Module

LIGHTPASS® series



NOVASTACK® series



Board-to-Board Connector



Power Connector/Terminal

AP series

ISH® series



MINIFLEX® series

EVAFLEX® series



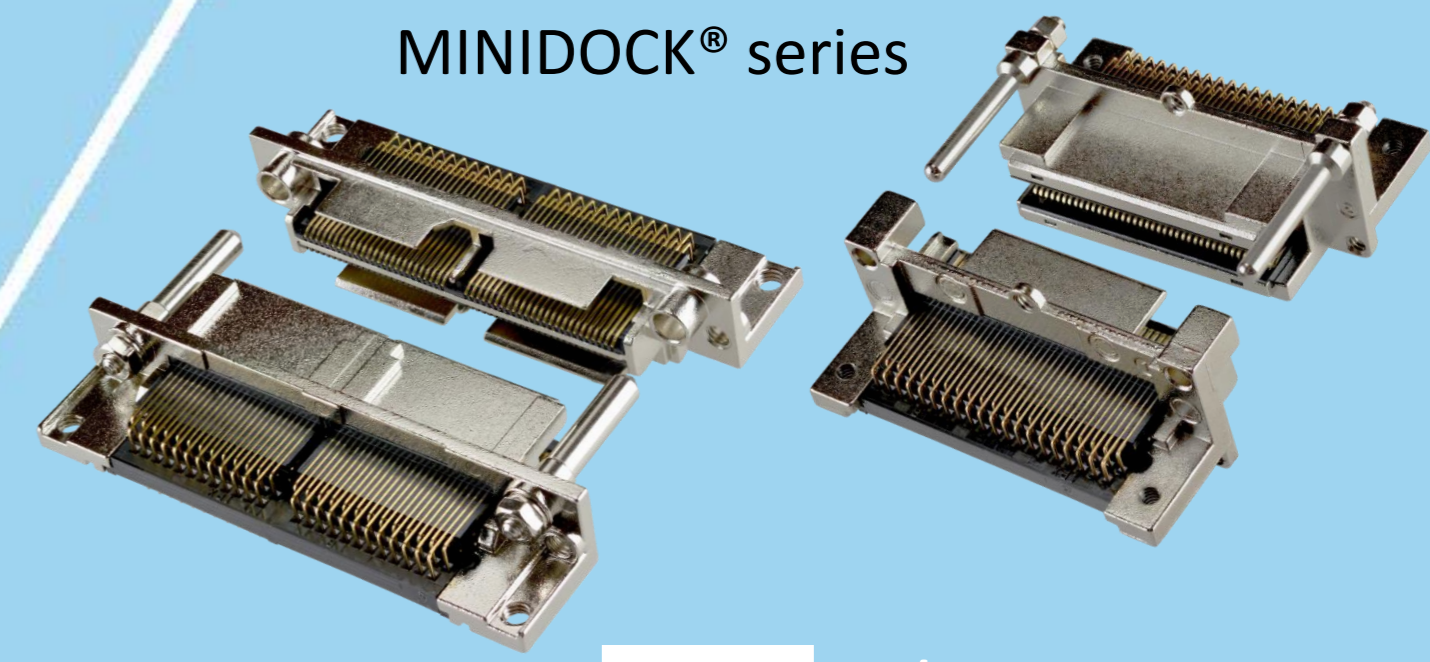
FPC FFC Connector



Inquiry



MINIDOCK® series



I/O Connector

I-PEX, MHF, CABLINE, LIGHTPASS, NOVASTACK, ISH, IARPB, MINIFLEX, EVAFLEX, MINIDOCKS and ZenShield are registered trademarks of I-PEX Inc. Please note that the contents in the catalog might be changed without prior notification. I-PEX Inc. assumes no responsibility for any inaccuracies or obligation to update information on these documents. Please be sure to read and understand the latest "Precautions for Use" and "Instruction Manual" before you use our products. We shall not be responsible for any defects, damages or troubles in case you use our products without following the precautions for use. Please feel free to contact our sales representatives when you use our products for any applications that require very high reliability and safety, or that relate to human life (ex. nuclear power control, aerospace, transportation, medical equipment, safety equipment etc.).

Contact your sales representative or more detailed information.

www.i-pex.com



I-PEX

© I-PEX Inc. 2024
All rights reserved